OFF-LINE POWER SUPPLY CONTROLLER

FEATURES

- **Transformerless Off-Line Power Supply**
- **Wide 100-VDC to 400-VDC Allowable Input Range**
- **Fixed 5-VDC or Adjustable Low-Voltage Output**
- **Output Sinks 200 mA, Sources 150 mA Into a MOSFET Gate**
- **Uses Low-Cost SMD Inductors**
- **Short Circuit Protected**
- **Optional Isolation Capability**

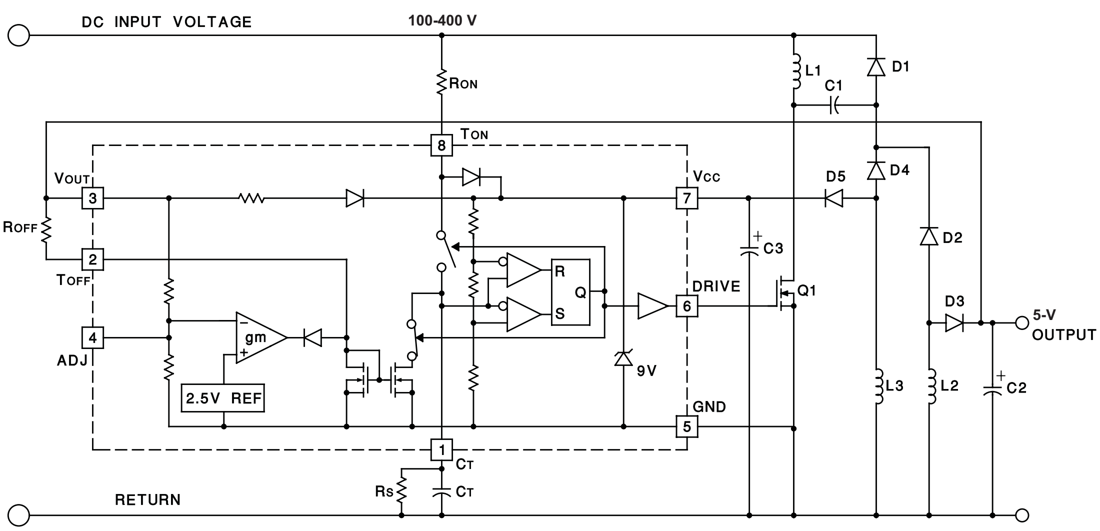
DESCRIPTION

The UCC3888 controller is optimized for use as an off-line, low-power, low-voltage, regulated bias supply. The unique circuit topology utilized in this device can be visualized as two cascaded flyback converters, each operating in the discontinuous mode, both driven from a single external power switch. The significant benefit of this approach is the ability to achieve voltage conversion ratios as high as 400 V to 2.7 V with no transformer and low internal losses.

The control algorithm utilized by the UCC3888 sets the switch on time inversely proportional to the input line voltage and sets the switch off time inversely proportional to the output voltage. This action is automatically controlled by an internal feedback loop and reference. The cascaded configuration allows a voltage conversion from 400 V to 2.7 V to be achieved with a switch duty cycle of 7.6%. This topology also offers inherent short circuit protection because as the output voltage falls to zero, the switch-off time approaches infinity.

The output voltage is set internally to 5 V. It can be programmed for other output voltages with two external resistors. An isolated version can be achieved with this topology as described further in Unitrode Application Note U-149.

TYPICAL APPLICATION



Note: This device incorporates patented technology used under license from Lambda Electronics, Inc.

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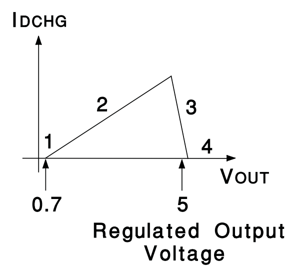
THEORY OF OPERATION

With reference to the application diagram below, when input voltage is first applied, the current through R_{ON} into T_{ON} is directed to V_{CC} where it charges the external capacitor, C3, connected to V_{CC}. As voltage builds on V_{CC}, an internal undervoltage lockout holds the circuit off and the output at DRIVE low until V_{CC} reaches 8.4 V. At this time, DRIVE goes high, turning on the power switch, Q1, and redirecting the current into T_{ON} to the timing capacitor, C_T. C_T charges to a fixed threshold with a current I_{CHG} = 0.8 • (V_{IN} – 4.5 V)/R_{ON}. Because DRIVE is high only as long as C_T charges, the power switch on time will be inversely proportional to line voltage. This provides a constant (line voltage) • (switch on time) product.

At the end of the on time, Q1 is turned off, and the current through R_{ON} is again diverted to V_{CC}. Thus the current through R_{ON}, which charges C_T during the on time, contributes to supplying power to the chip during the off time.

The power switch off time is controlled by the discharge of C_T, which, in turn, is programmed by the regulated output voltage. The relationship between C_T discharge current, I_{DCHG}, and output voltage is illustrated as follows:



Region 1. When V_{OUT} = 0, the off time is infinite. This feature provides inherent short circuit protection. However, to ensure output voltage startup when the output is not a short, a high-value resistor, R_S, is placed in parallel with C_T to establish a minimum switching frequency.

Region 2. As V_{OUT} rises above approximately 0.7 V to its regulated value, I_{DCHG} is defined by R_{OFF}, and is equal to:

I_{DCHG} = (V_{OUT}– 0.7V) / R_{OFF}

As V_{OUT} increases, I_{DCHG} increases reducing off time. The operating frequency increases and V_{OUT} rises quickly to its regulated value.

Region 3. In this region, a transconductance amplifier reduces I_{DCHG} to maintain a regulated V_{OUT}.

Region 4. If V_{OUT} should rise above its regulation range, I_{DCHG} falls to zero and the circuit returns to the minimum frequency established by R_S and C_T.

The range of switching frequencies is established by R_{ON}, R_{OFF}, R_S, and C_T as follows:

Frequency = 1/(T_{ON} + T_{OFF})

T_{ON} = R_{ON}• C_T• 4.6 V/(V_{IN} – 4.5 V)

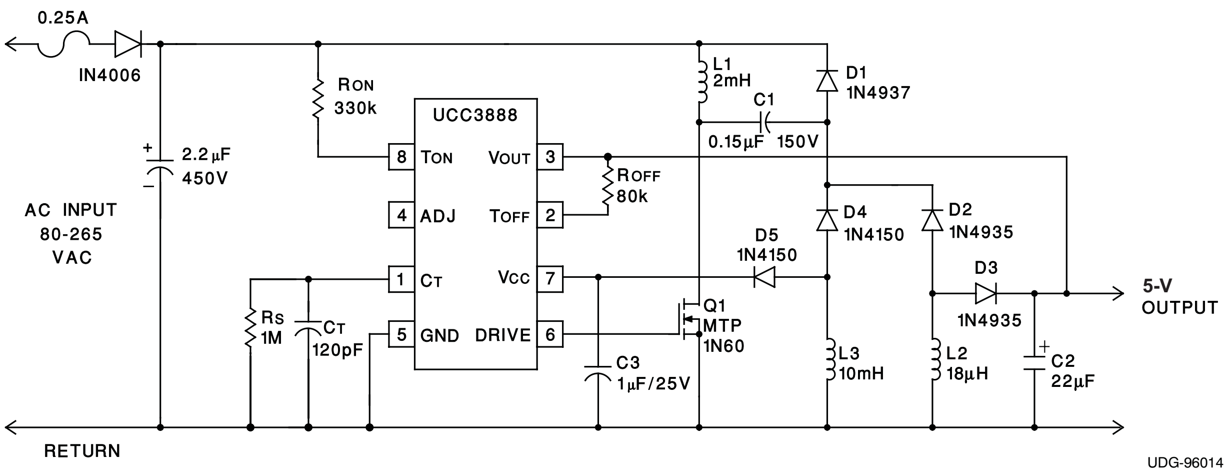
T_{OFF} (max) = 1.4 • R_S• C_T Regions 1 and 4

T_{OFF} = R_{OFF}• C_T• 3.7 V/(V_{OUT} – 0.7 V) Region 2, excluding the effects of R_S, which have a minimal impact on T_{OFF}.

The above equations assume that V_{CC} equals 9 V. The voltage at T_{ON} increases from approximately 2.5 V to 6.5 V while C_T is charging. To take this into account, V_{IN} is adjusted by 4.5 V in the calculation of T_{ON}. The voltage at T_{OFF} is approximately 0.7 V.

DESIGN EXAMPLE

The UCC3888 regulates a 5 volt, 1 Watt nonisolated DC output from AC inputs between 80 and 265 volts. In this example, the IC is programmed to deliver a maximum on time gate drive pulse width of 2.2 microseconds which occurs at 80 VAC. The corresponding switching frequency is approximately 100 kHz at low line, and overall efficiency is approximately 50%. Additional design information is available in Unitrode Application Note U-149.

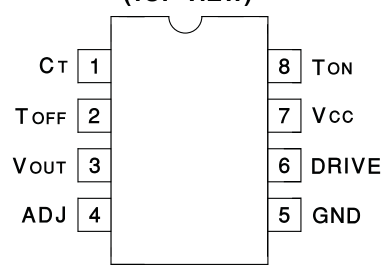


ABSOLUTE MAXIMUM RATINGS(1)

	VALUE	UNIT
I_{CC}	8	mA
Current into T_{ON} Pin	1.5	
Voltage on V_{OUT} Pin	20	V
Current into T_{OFF} Pin	250	µA
Storage temperature	–65 to 150	°C

(1) Unless otherwise indicated, voltages are referenced to ground and currents are positive into, negative out of, the specified terminals.

N OR J, D PACKAGE
(TOP VIEW)



ELECTRICAL CHARACTERISTICS

Unless otherwise stated, these specifications hold for T_A = 0°C to 70°C for the UCC3888, and –40°C to 85°C for the UCC2888. No load at DRIVE pin (C_{LOAD} = 0).

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
General					
V_{CC} Zener voltage	I_{CC} < 1.5 mA	8.6	9	9.3	V
Startup current	V_{OUT} = 0		150	250	µA
Operating current $I(V_{CC})$	$V_{CC} = V_{CC(zener)}$ – 100 mV, F = 150 kHz		1.2	2.5	mA
Under-Voltage-Lockout					
Start threshold	V_{OUT} = 0	8	8.4	8.8	
Minimum operating voltage after start	V_{OUT} = 0	6	6.3	6.6	V
Hysteresis	V_{OUT} = 0	1.8			
Oscillator					
Amplitude	V_{CC} = 9 V	3.5	3.7	3.9	V
C_T to DRIVE high propagation delay	Overdrive = 0.2 V		100	200	ns
C_T to DRIVE low propagation delay	Overdrive = 0.2 V		50	100	
Driver					
VOL	I = 20 mA, V_{CC} = 9 V		0.15	0.4	
	I = 100 mA, V_{CC} = 9 V		0.7	1.8	V
VOH	I = –20 mA, V_{CC} = 9 V	8.5	8.8		
	I = –100 mA, V_{CC} = 9 V	6.1	7.8		
Rise time	C_{LOAD} = 1 nF		35	70	ns
Fall time	C_{LOAD} = 1 nF		30	60	
Line Voltage Detection					
Charge coefficient: $I_{CHG}/I(T_{ON})$	VCT = 3 V, DRIVE = High, $I(T_{ON})$ = 1 mA	0.73	0.79	0.85	
Minimum line voltage for fault	R_{ON} = 330k	60	80	100	V
Minimum current $I(T_{ON})$ for fault	R_{ON} = 330k		220		µA
On time during fault	C_T = 150 pF, V_{LINE} = Min – 1 V		2		µs
Oscillator restart delay after fault			0.5		ms
V_{OUT} Error Amp					
V_{OUT} regulated 5 V (ADJ open)	V_{CC} = 9 V, $I_{DCHG} = I(T_{OFF})/2$	4.5	5	5.5	
Discharge ratio: I_{DCHG} / $I(T_{OFF})$	$I(T_{OFF})$ = 50 µA	0.9	1	1.1	V
Voltage at T_{OFF}	$I(T_{OFF})$ = 50 µA	0.6	0.95	1.3	
Regulation gm(1)	Max I_{DCHG} = 50 µA		2.4		mA/V
	Max I_{DCHG} = 125 µA	1.9	4.1	7	

(1) gm is defined as

$$\frac{\Delta ID_{CHG}}{\Delta V_{OUT}}$$

for the values of V_{OUT} when V_{OUT} is in regulation. The two points used to calculate gm are for I_{DCHG} at 65% and 35% of its maximum value.

PIN DESCRIPTIONS

ADJ: The ADJ pin is used to provide a 5-V regulated supply without additional external components. Other output voltages can be obtained by connecting a resistor divider between V_{OUT}, ADJ and GND. Use the formula:

$$V_{OUT} = 2.5\,V \bullet \frac{R1 + R2}{R2}$$

where R1 is connected between V_{OUT} and ADJ, and R2 is connected between ADJ and GND. R1 ∥ R2 should be less than 1 kΩ to minimize the effect of the temperature coefficient of the internal 30-kΩ resistors, which also connect to V_{OUT}, ADJ, and GND. See Figure 1.

C_T (timing capacitor): The signal voltage at C_T has a peak-to-peak swing of 3.7 V for 9 V V_{CC}. As the voltage at C_T crosses the oscillator upper threshold, DRIVE goes low. As the voltage on C_T crosses the oscillator lower threshold, DRIVE goes high.

DRIVE: This output is a CMOS stage capable of sinking 200 mA peak and sourcing 150 mA peak. The output voltage swing is 0 to V_{CC}.

GND (chip ground): All voltages are measured with respect to GND.

T_{OFF} (regulated output control): T_{OFF} sets the discharge current of the timing capacitor through an external resistor connected between V_{OUT} and T_{OFF}.

T_{ON} (line voltage control): T_{ON} serves three functions. When C_T is discharging (off time), the current through T_{ON} is routed to V_{CC}. When C_T is charging (on time), the current through T_{ON} is split 80% to set the C_T charge time and 20% to sense minimum line voltage, which occurs for a T_{ON} current of 220 µA. For a minimum line voltage of 80 V, R_{ON} is 330 kΩ.

The C_T voltage slightly affects the value of the charge current during the on time. During this time, the voltage at the T_{ON} pin increases from 2.5 V to 6.5 V.

V_{CC} (chip supply voltage): The supply voltage of the device at pin V_{CC} is internally clamped at 9 V. The device needs an external supply, from a source such as the rectified ac line or derived from the switching circuit. Precautions must be taken to ensure that total ICC does not exceed 8 mA.

V_{OUT} (regulated output): The V_{OUT} pin is directly connected to the power supply output voltage. When V_{OUT} is greater than V_{CC}, V_{OUT} bootstraps V_{CC}.

PIN DESCRIPTIONS (continued)

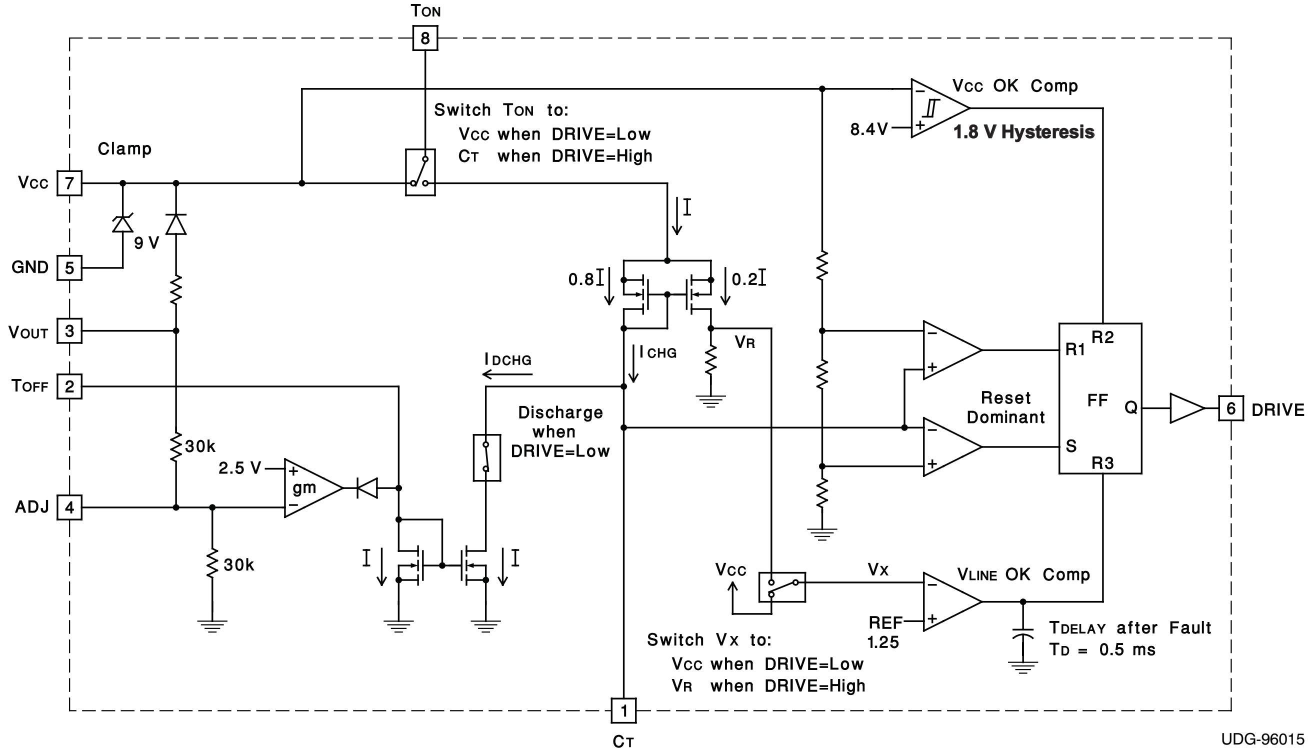
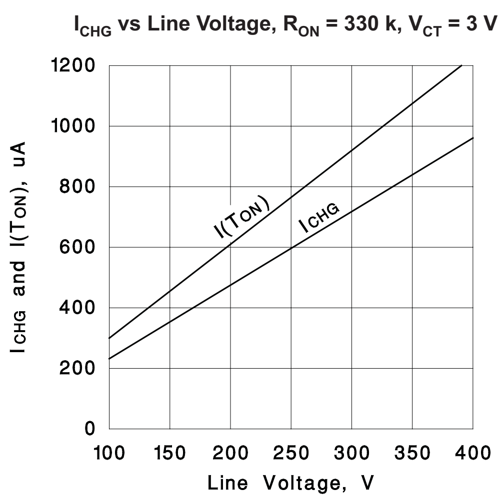
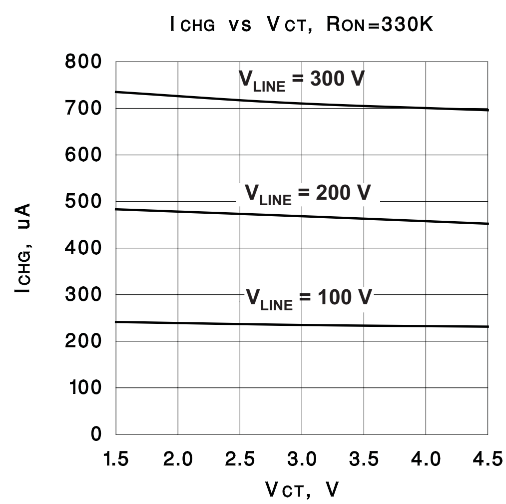


Figure 1. Block Diagram

TYPICAL CHARACTERISTICS





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
UCC3888N	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI	0 to 70	UCC3888N	
UCC3888NG4	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI	0 to 70	UCC3888N	

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

[4] Only one of markings shown within the brackets will appear on the physical device.

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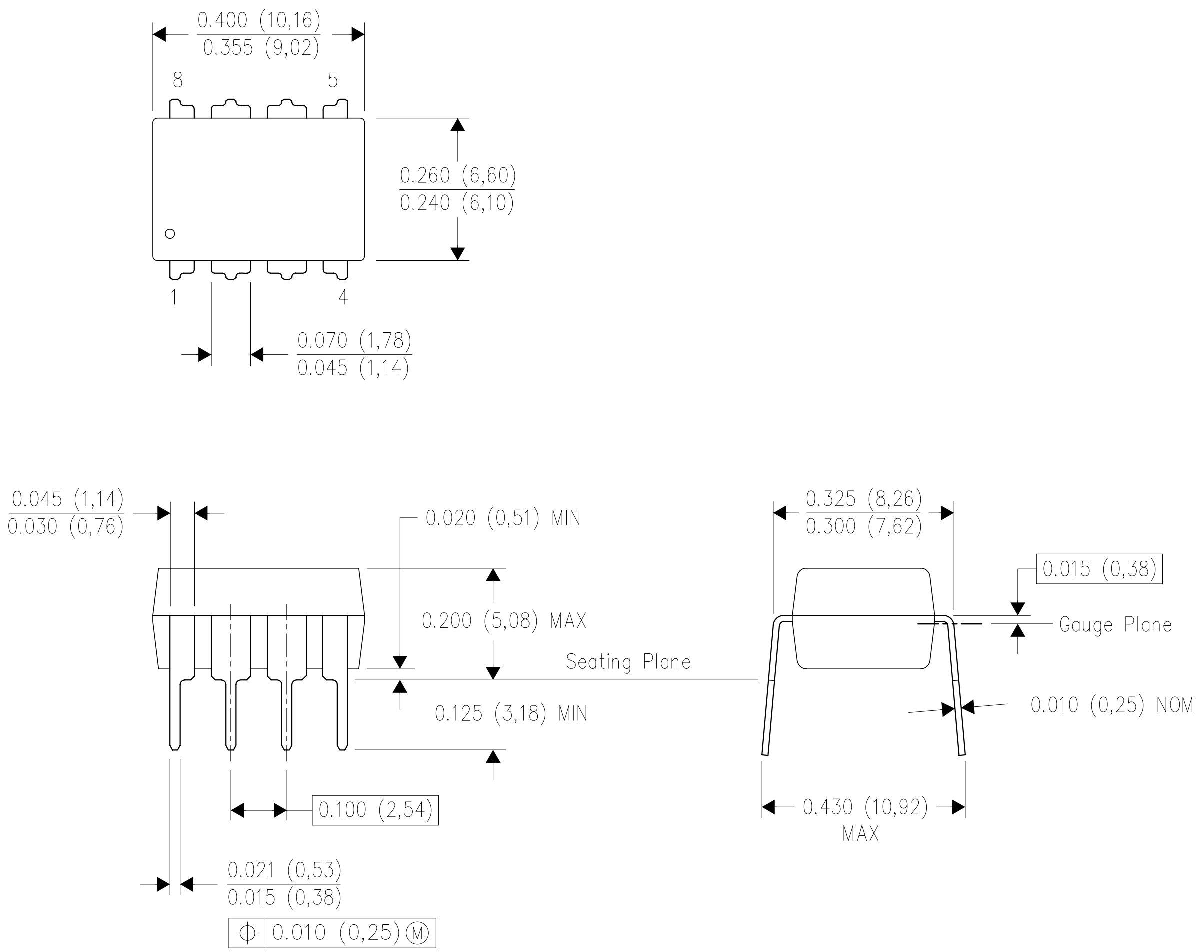
P (R–PDIP–T8) PLASTIC DUAL–IN–LINE PACKAGE



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NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001 variation BA.

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